



## Product/Process Change Notice - PCN 11\_0247 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

*Note: Revised fields are indicated by a red field name. See Appendix B for revision history.*

**PCN Title:** Addition of STATS ChipPAC Singapore as an Alternate Assembly Source for the 9x9mm LFCSP Package.

**Publication Date:** 05-Dec-2011

**Effectivity Date:** 04-Mar-2012 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

To correct BOM attachment to reflect new die attach.

### Description Of Change

ADI has qualified and will be utilizing Assembly subcontractor STATS ChipPAC Singapore for the 9x9mm LFCSP package. ADI has qualified STATS ChipPAC standard bill of materials. See attachment for BOM changes.

### Reason For Change

The use of ADI qualified STATS ChipPAC Singapore as an additional assembly site for this package will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

### Impact of the change (positive or negative) on fit, form, function & reliability

Utilization of additional subcontractor allows future shipments of affected material from either site. The device fit, form, function, and reliability, as specified by Product Data Sheets, will not be affected by this change.

### Product Identification *(this section will describe how to identify the changed material)*

Korea is the Country of Origin for Amkor (laser marked on the package) while Singapore will be the country of origin (laser marked on the package) for parts assembled at STATS ChipPAC.

### Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

### Supporting Documents

**Attachment 1: Type:** Detailed Change Description

ADI\_PCN\_11\_0247\_Rev\_A\_LFCSP BOM Set 9x9mm.pdf

**Attachment 2: Type:** Qualification Report Summary

ADI\_PCN\_11\_0247\_Rev\_A\_LFCSP Qual .pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

**Americas:** PCN\_Americas@analog.com

**Europe:** PCN\_Europe@analog.com

**Japan:** PCN\_Japan@analog.com

**Rest of Asia:** PCN\_ROA@analog.com

**Appendix A - Affected ADI Models****Existing Parts - Product Family / Model Number (12)**

AD5390 / AD5390BCPZ-3	AD5390 / AD5390BCPZ-3-REEL	AD5390 / AD5390BCPZ-3-REEL7	AD5390 / AD5390BCPZ-5	AD5390 / AD5390BCPZ-5-REEL
AD5390 / AD5390BCPZ-5-REEL7	AD5391 / AD5391BCPZ-3	AD5391 / AD5391BCPZ-5	AD5391 / AD5391BCPZ-5-REEL	AD5391 / AD5391BCPZ-5-REEL7
AD5392 / AD5392BCPZ-3	AD5392 / AD5392BCPZ-5			

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Rev Description</b>
Rev. -	09-Nov-2011	Initial Release
Rev. A	05-Dec-2011	To correct BOM attachment to reflect new die attach.

Analog Devices, Inc.

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